KINGTECH Kingtech Group Co., Ltd. ---- *Lcd Touchscreen Expert*

Add: 2nd Floor, Building C, Jia Huang Yuan Technical Park, Tiegang, Xixiang, Bao'an District, Shenzhen city, Guangdong province, P.R.China 518126.

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SPECIFICATION
FOR
LCD MODULE

MODULE NO: PV017703TD12C

Doc.Version:05

Customer Approval:

Add: 2nd Floor, Building C, Jia Huang Yuan Technical Park, Tiegang, Xixiang, Bao'an District, Shenzhen city, Guangdong province, P.R.China 518126.
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□ Accept □ Reject

YEEBO	NAME	SIGNATURE	DATE
Prepare	Electronic Engineer		2017-7-28
Check	Mechanical Engineer		2016-7-28
Verify			2016-7-28
Approval			

□APPROVAL FOR SPECIFICATIONS ONLY

■ APPROVAL FOR SPECIFICATIONS AND SAMPLE

Sample Version	DOC. Version	DATE	DESCRIPTION		CHANGED BY
A0	00	2015-12-2	Spec Only	First issue	覃锦伟
A0	01	2016-3.-14	Page 6	Change **6-1 Absolute Maximum Ratings**	qin
A0	02	2016-3-29	Page 8	Optical Characteristics	qin
A0	03	2016.5.4	Page 13	Add packing	qin
A1	04	2017.7.28	Page 5	Update LCM drawing ① Change the golden finger structure ② Change the stickiness of the tearing position	Zhao

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A2	05	2017.7.28	Page 5	Change the double-sided adhesive inside the backlight reflector, Add back adhesive drawing	Zhao

2. Table of Contents:

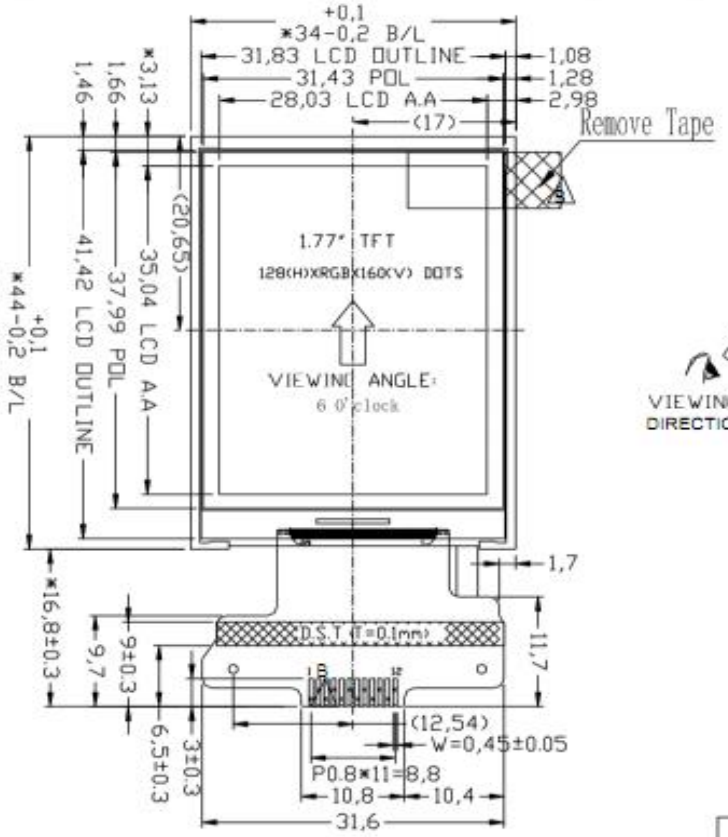
4. General Specification:

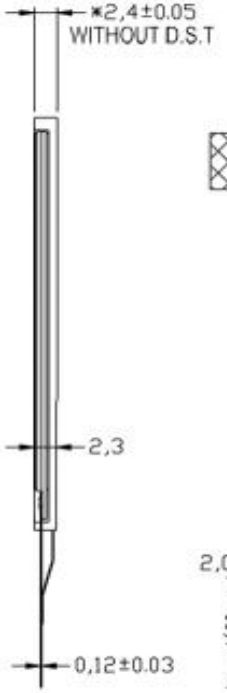
ITEM	CONTENTS
Module Size	34(W) * 44(H) * 2.4(T) mm
Display Size(Diagonal)	1.77 inch
Display Format	128(RGB)* 160 Pixels
Active Area	28.03(W) *35.04(H) mm
Pixel Pitch	0.073mm*0.219 mm
LCD Type	TFT (262K)/ Transmissive / NW
View Angle	6 O'clock
Controller IC	ST7735S
Weight	6g

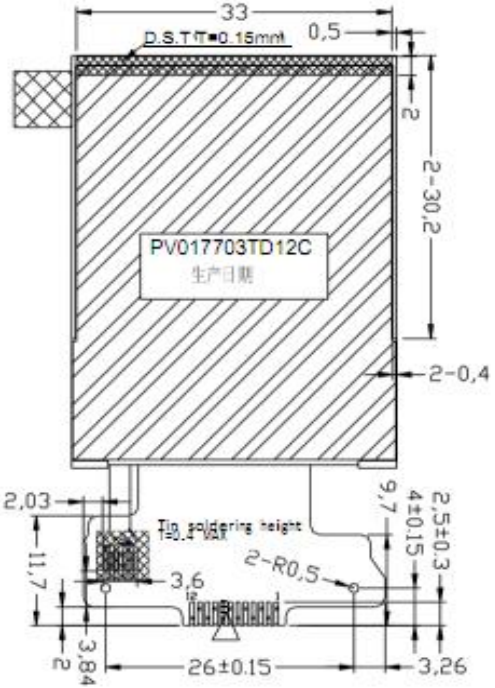
5. LCM drawing:

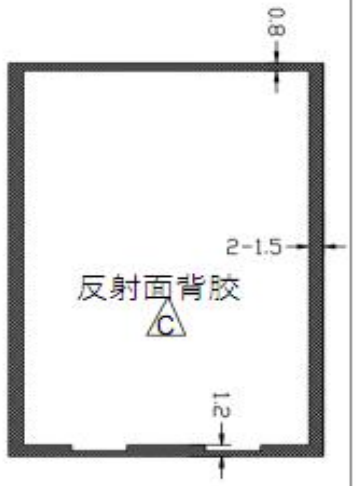
Count drawing & Spec.revision record during discussion with customer		
Rec.	Revision content description	Date
A	FIRST ISSUE	2015.06.25
B	取消FPC金手指上的外孔,更改脚手位的焊盘	2017.06.21
C	更改背光反射片内部双面胶	2017.07.28

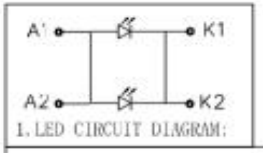
Pad No.	Pad Name
1	GND
2	VDD
3	NC
4	LCD-RS
5	SDA
6	LCD-CS
7	LCD-RST
8	SCL
9	LED-A1
10	LED-A2
11	LED-K2
12	LED-K1











1、Display type:TFT/Normal white
2、Display mode:Transmissive
3、Interface: SPI / Driver IC: ST7735S
4、The best Viewing direction: 6 O'CLOCK
5、Backlight: White LED(2-LED) / VF=2.8-3.4VF / IF=30mA
6、LCM Luminance: 250cd/m TYP
7、Operating temprature: -20° C ~ +70° C
8、Storage temprature: -30° C ~ +80° C
9、ROHS REQUEST
10、GENERAL TOLERANCE:±0.2

Kingtech Group Co.,Ltd	MOD. Name	PV017703TD12C				Sheet	1
						Of	1
	DESIGNED	CHECKED	VERIFIED	APPROVED	FILE NAME		
UNIT: mm / SIZE: A4 / SCALE: N-T-S					Count Dwg.		

6. Electrical Characteristics

6-1 Absolute Maximum Ratings (Ta=25℃ VSS=0V)

Item	Symbol	Min.	Type	Max.	Unit	Remark
Input Voltage	V_{CI}-V_{SS}	-0.3	-	4.8	Volt	Note1
Supply Voltage	V_{DDIO}-V_{SS}	-0.3	-	4.6	Volt	Note1
Operating Temperature	Topr	-20	-	+70	℃	-
Storage Temperature	Tstg	-30	-	+80	℃	-

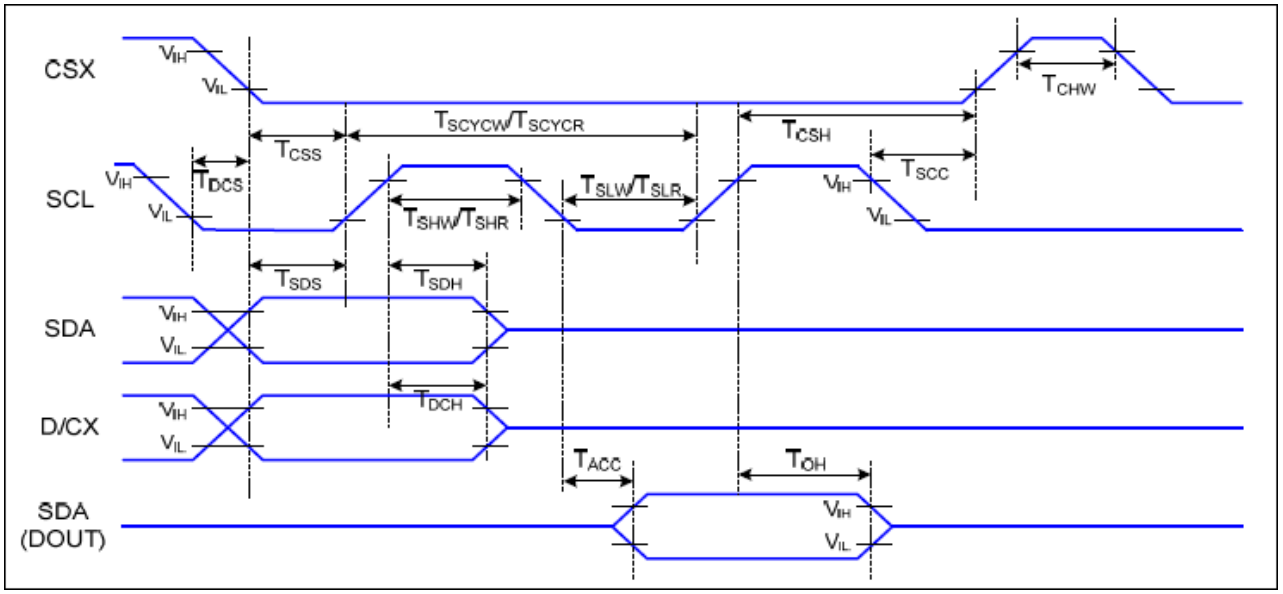
Note1: Absolute maximum rating is the limit value beyond which the IC maybe broken. They do not assure operations.

6-2 Operating Conditions (Ta=25℃)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Power Supply voltage	V_{CI}-V_{SS}	-	2.5	2.8	3.3	Volt
Input Voltage	V_{IH}	-	0.7 * V_{DDIO}	-	V_{DDIO}	V
	V_{IL}	-	V_{SS}	-	0.3 * V_{DDIO}	V
Power Supply Current for LCM	I_{DD}	V_{CI}=3.3V	-	4	-	mA

6-3 Timing Characteristics

6-3-1. Serial Interface Characteristics (4-line Serial)



Ta=25 ℃, VDDI=1.65~3.7V, VDD=2.5~4.8V

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
CSX	TCSS	Chip Select Setup Time (Write)	45		ns	
	TCSH	Chip Select Hold Time (Write)	45		ns	
	TCSS	Chip Select Setup Time (Read)	60		ns	
	TSCC	Chip Select Hold Time (Read)	65		ns	
	TCHW	Chip Select "H" Pulse Width	40		ns	
SCL	TSCYCW	Serial Clock Cycle (Write)	66		ns	-Write Command & Data Ram
	TSHW	SCL "H" Pulse Width (Write)	15		ns	
	TSLW	SCL "L" Pulse Width (Write)	15		ns	
	TSCYCR	Serial Clock Cycle (Read)	150		ns	-Read Command & Data Ram
	TSHR	SCL "H" Pulse Width (Read)	60		ns	
	TSLR	SCL "L" Pulse Width (Read)	60		ns	
D/CX	TDCS	D/CX Setup Time	10		ns	
	TDCH	D/CX Hold Time	10		ns	
SDA (DIN) (DOUT)	TSDS	Data Setup Time	10		ns	For Maximum CL=30pF For Minimum CL=8pF
	TSDH	Data Hold Time	10		ns	
	TACC	Access Time	10	50	ns	
	TOH	Output Disable Time	15	50	ns	

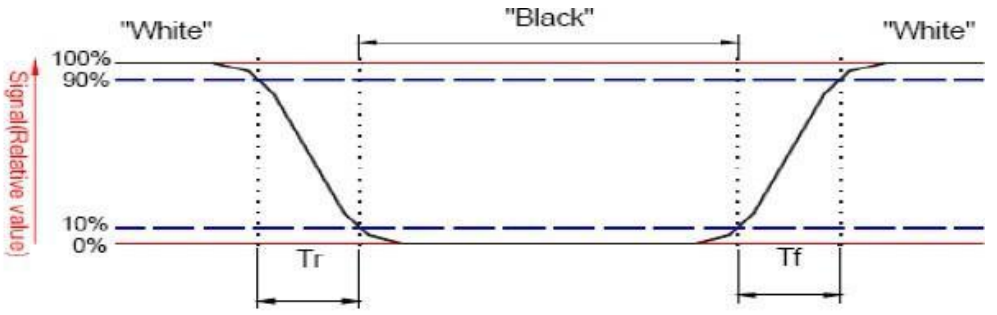
7. Optical Characteristics:

Item		Symbol	Conditions	Specifications			Unit	Note
				Min	Typ	Max		
Transmittance (Without PL)		T(%)	–	6.21	6.9		-	5
Contrast Ratio		CR	Θ =0 Normal Viewing angle	350	500			3,7
Response time		TR+TF	–	30	60		ms	6
Viewing angle	Hor.	Θx+	CR≧10	55	60		deg.	3,7,8
		Θx-		55	60			
	Ver.	Θy+		55	60			
		Θy-		50	55			

Color of CIE Coordinate:

Item		Symbol	Condition	Min.	Typ.	Max.
Chromaticity Coordinates (Transmissive)	Red	x	θ = 0° LED Backlight Color Degree	0.590	0.610	0.620
		y		0.309	0.329	0.349
	Green	x		0.279	0.299	0.319
		y		0.547	0.567	0.587
	Blue	x		0.093	0.143	0.192
		y		0.072	0.122	0.173
	White	x		0.288	0.308	0.328
		y		0.307	0.327	0.347

Note 1: Ambient temperature = 25°C.
Note 2: To be measured in dark room after LED backlight warm up 5 minutes.
Note 3: To be measured with a viewing cone of 2°by Topcon luminance meter BM-5A.
Note 4: To be measured with Otsuta chromaticity meter LCF-2100M, CF only measure with C light
Note 5: CDY shipping status is cell without polarizer. Transmittance of Specification is cell with polarizer
Note 6: Definition of response time:
The output signals of TRD-100 are measured when the input signals are changed to "White" (falling time) and from "White" to "Black" (rising time), respectively. The interval is between the 10% and 90% of amplitudes. Refer to figure as below.

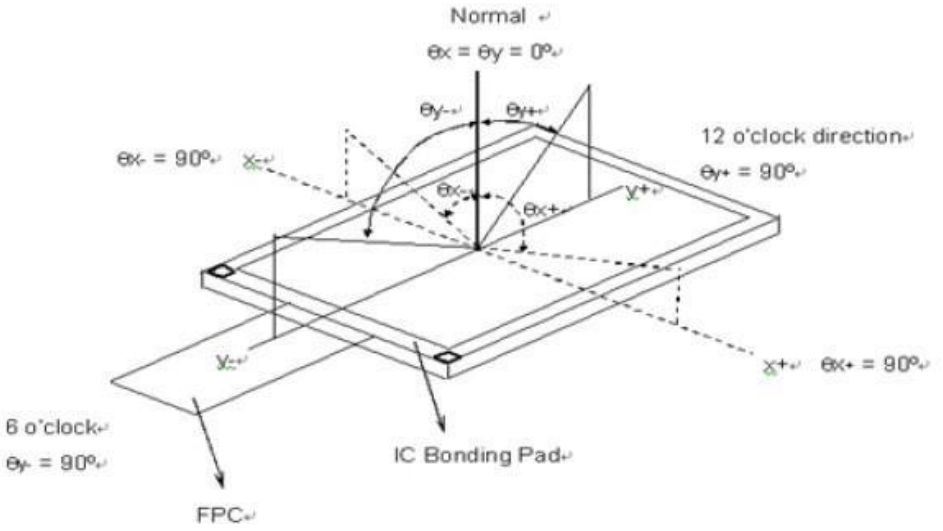


Note 7: Definition of contrast ratio:

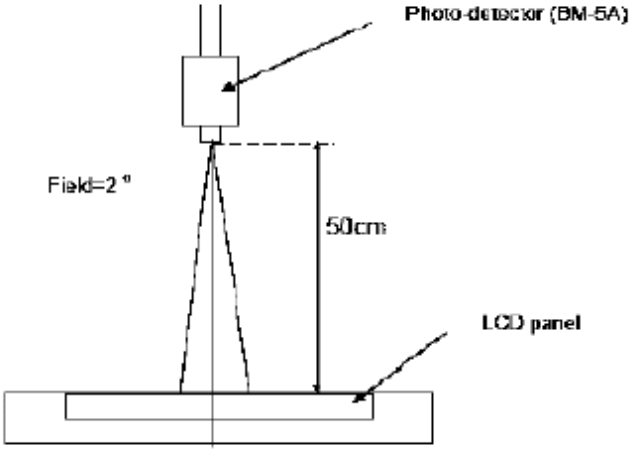
Contrast ratio is calculated by the following formula.

$$\text{Contrast ratio (CR)} = \frac{\text{Brightness on the "white" state}}{\text{Brightness on the "black" state}}$$

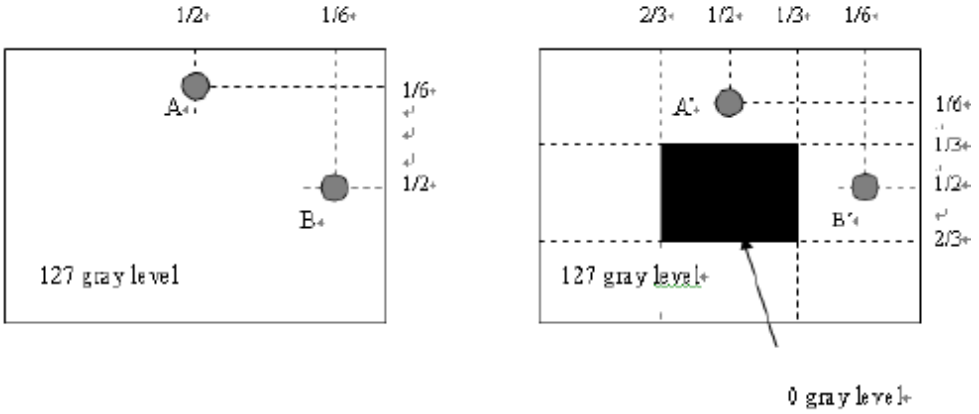
Note 8: Definition of viewing angle



Note 9: Optical characteristic measurement setup.



Note 10:



I LA-LA' I / LA x 100%= 2% max., LA and LA' are brightness at location A and A'
I LB-LB' I / LB x 100%= 2% max., LB and LB' are brightness at location B and B'

8. Interface Pin Assignment:

8-1 LCM FPC Interface

Pin NO.	Symbol	Level	Remark
1	GND	L	Ground
2	VDD	H	Power supply(2.5-3.3V)
3	NC		Not connect
4	RS	H/L	Data /command select pin
5	SDA	H/L	serial input
6	CS	H/L	Chip select input pin
7	REST	H/L	Hardware reset pin
8	SCL	H/L	SPI clock input pin
9	LEDA1	H	Backlight+
10	LEDA2	H	Backlight+
11	LEDK1	L	Backlight-
12	LEDK2	L	Backlight-

9. Backlight:

1. Standard Lamp Styles (Edge Lighting Type):
   The LED chips are distributed over the edge light area of the illumination unit, which gives the less power consumption:

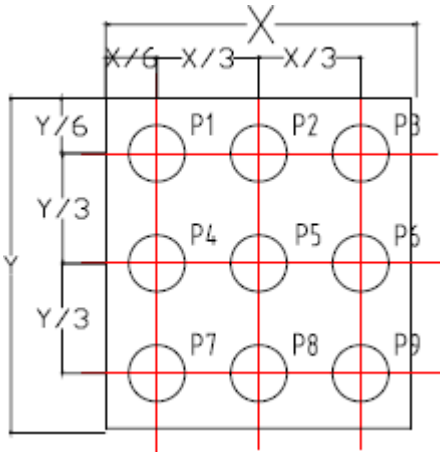
2. The Main Advantages of the LED Backlight are as following:
   2.1 The brightness of the backlight can simply be adjusted.
   By a resistor or a potentiometer.

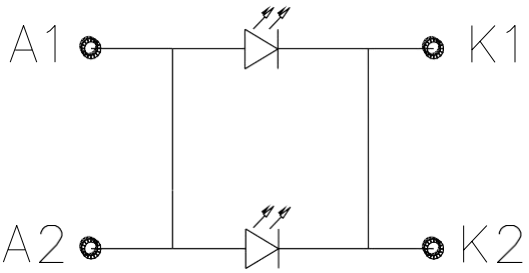
3. Data About LED Backlight:

PARAMETER	Sym.	Min.	Typ.	Max.	Unit	Test Condition	Note
Supply Current	I	-	30	-	mA	V=3.4V	
Supply Voltage	V	2.8	3.2	3.4	V	If=30mA	
Reverse Voltage	VR	-	-	5.0	V	-	
Luminous Intensity for LCM	IV		250	-	Cd/m^2	If=30mA	2
Uniformity for LCM	-	80	-	-	%		3
Life Time	-	50000	-	-	Hr.		4
Color	White						

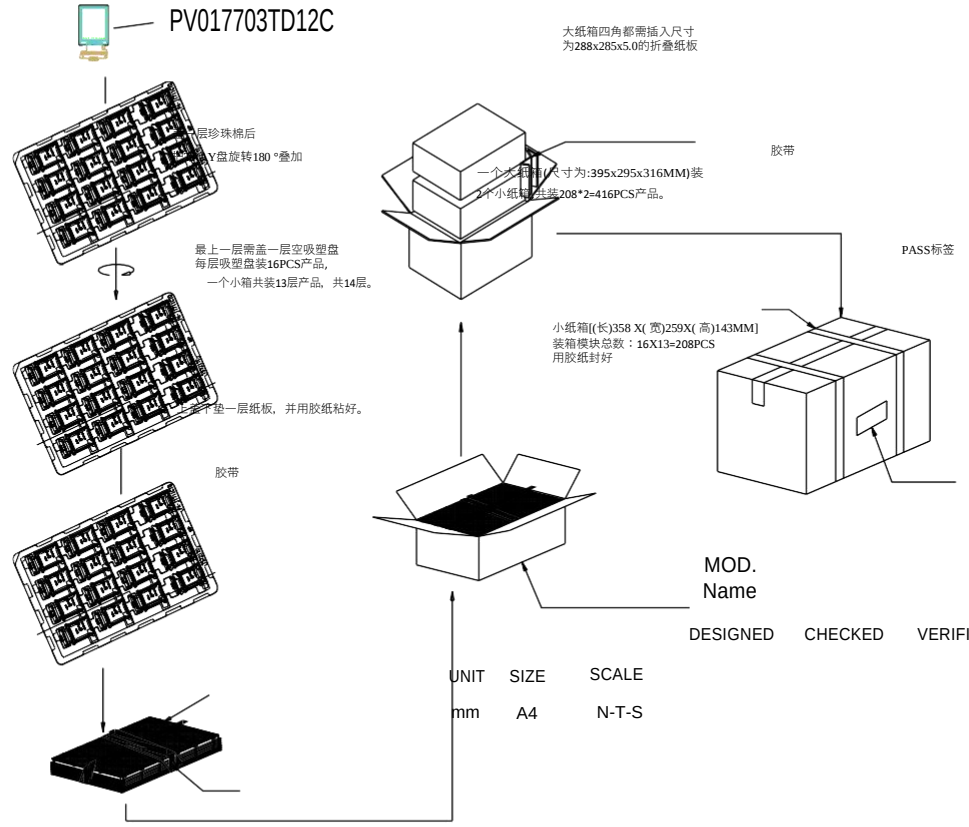
NOTE:
1. Backlight Only
2. Average Luminous Intensity of P1-P9
3. Uniformity = Min/Max * 100%
4. LED life time defined as follows: The final brightness is at 70% of original brightness

Measured Method: (X*Y: Light Area) **Internal Circuit Diagram**





Rec.	Revision content description	Date
A1		2016.06.03



MOD.
Name

DESIGNED	CHECKED	VERIFIED	APPROVED	FILE NAME
				PACKING

UNIT	SIZE	SCALE
mm	A4	N-T-S

Sheet 1
Of 1

11. Standard Specification for Reliability:

11–1. Standard Specifications for Reliability of LCD Module

No	Item	Description
01	High temperature operation	The sample should be allowed to stand at 70℃ for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
02	Low temperature operation	The sample should be allowed to stand at -20℃ for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
03	High temperature storage	The sample should be allowed to stand at 80℃ for 200 hours under no-load condition, and then returning it to normal temperature condition, and allowing it stand for 2 hours.
04	Low temperature storage	The sample should be allowed to stand at -30℃ for 200 hours under no-load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours.
05	Moisture storage	The sample should be allowed to stand at 50℃±5℃,90%RH MAX for 120 hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours.
06	Thermal shock storage	The sample should be allowed to stand the following 10 cycles : -30℃ for 30 minutes → normal temperature for 5 minutes → +80℃ for 30 minutes → normal temperature for 5 minutes, as one cycle.
07	Packing vibration	Frequency range : 10Hz ~ 55Hz Amplitude of vibration : 1.5mm Sweep time: 12 min X,Y,Z 2 hours for each direction.
08	Packing drop test	According to ISTA 1A 2001.
09	Electrical Static Discharge	Air: ±4KV 150pF/330Ω 5 times
		Contact: ±2KV 150pF/330Ω 5 time

*Sample size for each test item is 3~5pcs

11 - 2. Testing Conditions and Inspection Criteria

For the final test the testing sample must be stored at room temperature for 24 hours, after the tests listed in Table 11.2, Standard specifications for Reliability have been executed in order to ensure stability.

No	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

11- 3. MTBF

MTBF	Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature (25±5 ℃), normal humidity (50±10% RH), and in area not exposed to direct sun light.

12. Specification of Quality Assurance:

12-1. Purpose

This standard for Quality Assurance should affirm the quality of LCD module products to supply to purchaser by Kingtech Group Co.,Ltd (Supplier).

12-2. Standard for Quality Test

a. Inspection:

Before delivering, the supplier should take the following tests, and affirm the quality of product.

b. Electro-Optical Characteristics:

According to the individual specification to test the product.

c. Test of Appearance Characteristics:

According to the individual specification to test the product.

d. Test of Reliability Characteristics:

According to the definition of reliability on the specification for testing products.

e. Delivery Test:

Before delivering, the supplier should take the delivery test.

(i) Test method: According to MIL-STD105E.General Inspection Level Ⅱ take a single time.

(ii) The defects classify of AQL as following:

Major defect: AQL = 0.65

Minor defect: AQL = 2.5

Total defects: AQL = 2.5

12-3. Non- conforming Analysis & Deal With Manners

a. Non- conforming Analysis:

(i) Purchaser should supply the detail data of non- conforming sample and the non-conforming.

(ii) After accepting the detail data from purchaser, the analysis of non- conforming should be finished in two weeks.

(iii) If supplier can not finish analysis on time, must announce purchaser before 3 days.

b. Disposition of non- conforming:

(i) If find any product defect of supplier during assembly time, supplier must change the good product for every defect after recognition.

(ii) Both supplier and customer should analyze the reason and discuss the disposition of non- conforming when the reason of nonconforming is not sure.

12-4. Agreement items

Both sides should discuss together when the following problems happen.

a. There is any problem of standard of quality assurance, and both sides should think that must be modified.
b. There is any argument item which does not record in the standard of quality assurance.
c. Any other special problem.

12-5. Standard of The Product Appearance Test

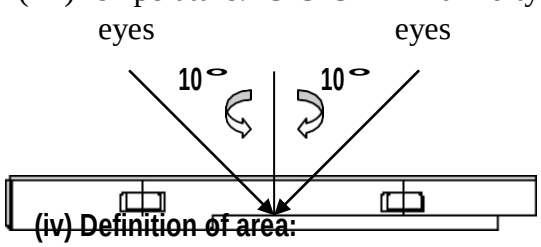
a. Manner of appearance test:

(i) The test must be under 20W × 2 or 40W fluorescent light, and the distance of view must be at 30±5cm.

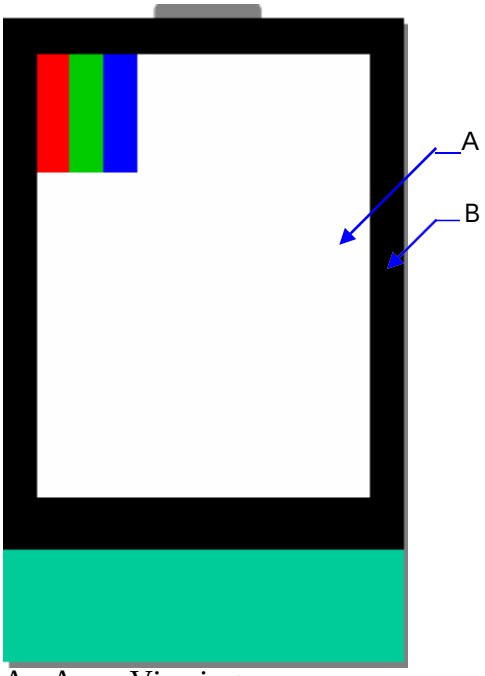
(ii) When test the model of transmissive product must add the reflective plate.

(iii)The test direction is base on around 10°of vertical line.

(iiii)Temperature: 25±5℃ Humidity: 60±10%RH



(iv) Definition of area:



A. Area: Viewing area.

B. Area: Out of viewing area.
(Outside viewing area)

b. Basic principle:

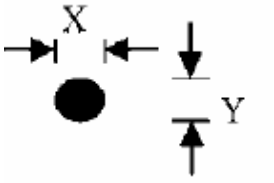
(i) It will accord to the AQL when the standard can not be described.

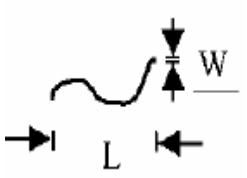
(ii) The sample of the lowest acceptable quality level must be discussed by both supplier and customer when any dispute happened.

(iii) Must add new item on time when it is necessary.

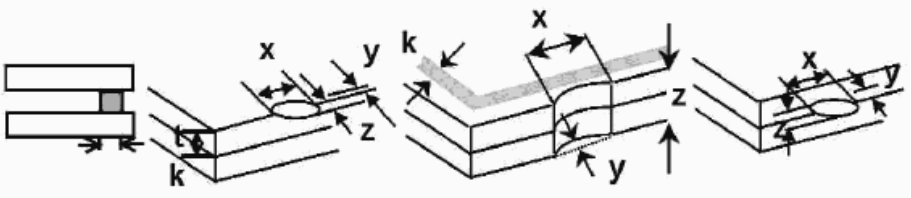
c. Standard of inspection: (Unit: mm)

12-6. Inspection specification

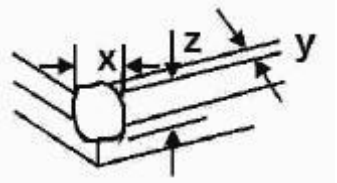
<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>01</td><td>Electrical Testing</td><td>1.1 Missing vertical, horizontal segment, segment contrast defect.
1.2 Missing character, dot or icon.
1.3 Display malfunction.
1.4 No function or no display.
1.5 Current consumption exceeds product specifications.
1.6 LCD viewing angle defect.
1.7 Mixed product types.
1.8 Flicker</td><td>0.65</td></tr>
<tr><td>02</td><td>Black or White spots or Bright spots or Color spots on LCD (Display only)</td><td>2.1 White and black or color spots on display ≦ 0.25mm, no more than Five spots.
2.2 Densely spaced: No more than three spots within 3mm.</td><td>2.5</td></tr>
<tr><td rowspan="2">03</td><td rowspan="2">LCD and Touch Panel black spots, white spots, contamination (non – display)</td><td>3.1 Round type: As following drawing
Φ = (X+Y) / 2
 

<table>
<tr><th>Size(mm)</th><th>Acceptable Q'ty</th></tr>
<tr><td>Φ≦0.10</td><td>Accept no dense</td></tr>
<tr><td>0.10< Φ≦0.20</td><td>2</td></tr>
<tr><td>0.20< Φ≦0.25</td><td>2</td></tr>
<tr><td>0.25< Φ≦0.30</td><td>1</td></tr>
<tr><td>0.30< Φ</td><td>0</td></tr>
</table>
* Densely spaced: No more than two spots within 3mm.</td><td>2.5</td></tr>
<tr><td>3.2 Line type: (As following drawing)
 

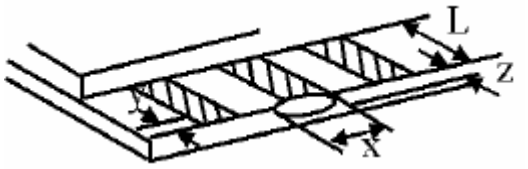
<table>
<tr><th>Length(mm)</th><th>Width(mm)</th><th>Acceptable Q'ty</th></tr>
<tr><td>---</td><td>W≦0.02</td><td>Accept no dense</td></tr>
<tr><td>L≦3.0</td><td>0.02<W≦0.05</td><td rowspan="2">2</td></tr>
<tr><td>L≦2.5</td><td>0.03<W≦0.08</td></tr>
<tr><td>---</td><td>0.08<W</td><td>Rejection</td></tr>
</table>
* Densely spaced: No more than two lines within 3mm.</td><td>2.5</td></tr>
</table>

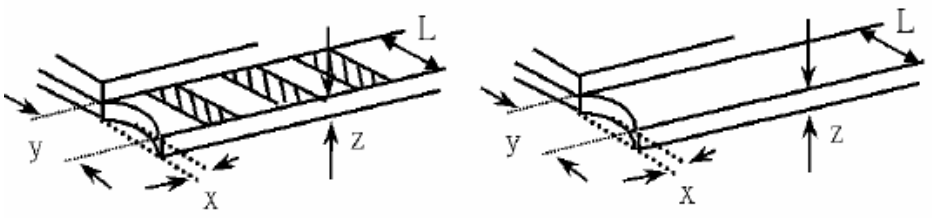
<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>04</td><td>Polarizer bubbles</td><td>If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction
<table>
<tr><th>Size Φ(mm)</th><th>Acceptable Q'ty</th></tr>
<tr><td>Φ≦0.20</td><td>Accept no dense</td></tr>
<tr><td>0.20< Φ≦0.50</td><td>3</td></tr>
<tr><td>0.50< Φ≦1.00</td><td>2</td></tr>
<tr><td>1.00< Φ</td><td>0</td></tr>
<tr><td>Total Q'ty</td><td>3</td></tr>
</table></td><td>2.5</td></tr>
<tr><td>05</td><td>Scratches</td><td>Follow NO.3 -2 Line Type.</td><td></td></tr>
<tr><td>06</td><td>Chipped glass</td><td>Symbols:
x: Chip length y: Chip width z: Chip thickness
k: Seal width t: Glass thickness a: LCD side length
L: Electrode pad length
6.1 General glass chip:
6.1.1 Chip on panel surface and crack between panels:
 

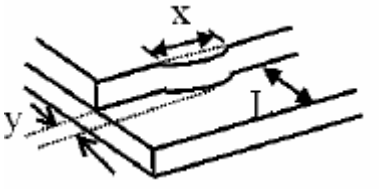
<table>
<tr><th>z: Chip thickness</th><th>y: Chip width</th><th>x: Chip length</th></tr>
<tr><td>Z≦1/2t</td><td>Not over viewing area</td><td>x≦1/8a</td></tr>
<tr><td>1/2t< z≦2t</td><td>Not exceed 1/3k</td><td>x≦1/8a</td></tr>
</table>
⊙
Unit: mm
⊙ If there are 2 or more chips, x is the total length of each chip

6.1.2 Corner crack:
 

<table>
<tr><th>z: Chip thickness</th><th>y: Chip width</th><th>x: Chip length</th></tr>
<tr><td>Z≦1/2t</td><td>Not over viewing area</td><td>x≦1/8a</td></tr>
<tr><td>1/2t< z≦2t</td><td>Not exceed 1/3k</td><td>x≦1/8a</td></tr>
</table>
⊙
Unit: mm
⊙ If there are 2 or more chips, x is the total length of each chip</td><td>2.5</td></tr>
</table>

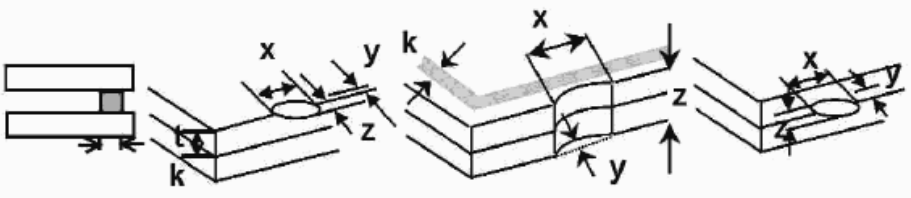
<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>07</td><td>Glass crack</td><td>
Symbols:
x: Chip length y: Chip width z: Chip thickness
k: Seal width t: Glass thickness a: LCD side length
L: Electrode pad length
7.2 Protrusion over terminal:
7.2.1 Chip on electrode pad:


<table>
<tr><th>y: Chip width</th><th>x: Chip length</th><th>z: Chip thickness</th></tr>
<tr><td>y≦0.5mm</td><td>x≦1/8a</td><td>0< z≦t</td></tr>
</table>
7.2.2
Non-conductive portion:


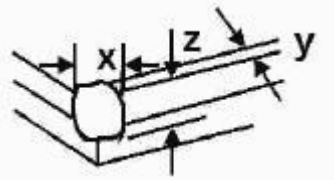
<table>
<tr><th>y: Chip width</th><th>x: Chip length</th><th>z: Chip thickness</th></tr>
<tr><td>y≦L</td><td>x≦1/8a</td><td>0< z≦t</td></tr>
</table>
⊙ If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.
⊙ If the product will be heat sealed by the customer, the alignment mark must mot be damaged.
7.2.3 Substrate protuberance and internal crack


<table>
<tr><th>y: width</th><th>x: length</th></tr>
<tr><td>y≦1/3L</td><td>X≦a</td></tr>
</table>
</td><td>2.5</td></tr>
</table>

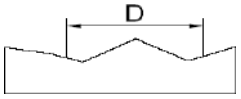
NO	Item	Criterion	AQL
08	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
09	Backlight elements	9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong.	2.5 2.5 0.65
10	Bezel	Bezel must comply with product specifications.	2.5
11	PCB、COB	11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart.	2.5 2.5 2.5 2.5 0.65 0.65
12	FPC	12.1 FPC terminal damage ≦ 1/2 FPC terminal width and can not affect the function , we judge accept. 12.2 FPC alignment hole damage ≦ 1/2 alignment area and can not affect the function , we judge accept.	2.5 2.5
13	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or icicle. 13.2 No short circuits in components on PCB or FPC.	2.5 0.65

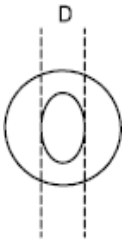
<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>14</td><td>Touch Panel Chipped glass</td><td>
Symbols:
x: Chip length y: Chip width z: Chip thickness
k: Seal width t: Touch Panel Total thickness a: LCD side length
L: Electrode pad length
14.1 General glass chip:
14.1.1 Chip on panel surface and crack between panels:


<table>
<tr><th>z: Chip thickness</th><th>y: Chip width</th><th>x: Chip length</th></tr>
<tr><td>Z≦t</td><td>≦1/2 k and not over viewing area</td><td>x≦1/8a</td></tr>
</table>
⊙ Unit: mm
⊙ If there are 2 or more chips, x is the total length of each chip

14.1.2 Corner crack:


<table>
<tr><th>z: Chip thickness</th><th>y: Chip width</th><th>x: Chip length</th></tr>
<tr><td>z≦t</td><td>≦1/2 k and not over viewing area</td><td>x≦1/8a</td></tr>
</table>
⊙ Unit: mm
⊙ If there are 2 or more chips, x is the total length of each chip
</td><td>2.5</td></tr>
</table>

<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>15</td><td>Touch Panel(Fish eye、dent and bubble on film)</td><td>
<table>
<tr><th>SIZE(mm)</th><th>Acceptable Q'ty</th></tr>
<tr><td>Φ≦0.2</td><td>Accept no dense</td></tr>
<tr><td>0.2< D ≦0.4</td><td>5</td></tr>
<tr><td>0.4< D ≦0.5</td><td>2</td></tr>
<tr><td>0.5< D</td><td>0</td></tr>
</table>




</td><td>2.5</td></tr>
<tr><td>16</td><td>Touch Panel Newton ring</td><td>Newton ring dimension ≦ 1/2 touch panel area and not affect font and line distortion(≦2.5%) , it is acceptable.</td><td>2.5</td></tr>
<tr><td>17</td><td>Touch Panel Linearity</td><td>Less than 2.5% is acceptable.</td><td>2.5</td></tr>
<tr><td>18</td><td>LCD Ripple</td><td>Touch the touch panel , can not see the LCD ripple.
Pen: R 1.0mm silicon rubber.
Operation Force: 80g</td><td>2.5</td></tr>
<tr><td>19</td><td>General appearance</td><td>19.1 Pin type must match type in specification sheet.
19.2 LCD pin loose or missing pins.
19.3 Product packaging must the same as specified on packaging specification sheet.
19.4 Product dimension and structure must conform to product specification sheet.</td><td>0.65
0.65
0.65
0.65</td></tr>
</table>

13. Handling Precaution:

13-1 Handling of LCM

- Don't give external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance. Must not lick and swallow. when the liquid is attach to your hand, skin, cloth etc. Wash it out thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads,the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

13-2 Storage

- Store in an ambient temperature of 25±10℃, and in a relative humidity of 50±10%RH. Don't expose to sunlight or fluorescent light.
- Storage in a clean environment, free from dust, active gas, and solvent.
- Store in anti-static electricity container.
- Store without any physical load.

13-3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: No higher than 280±10 ℃ and less than 3 sec during Hand soldering.
- Rewiring: no more than 2 times.